

650V N-Channel MOSFET

Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

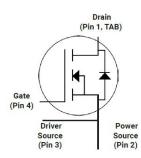
Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Simple to drive with Standard Gate Drive
- 100% avalanche tested
- Maximum junction temperature of 150°C
- ROHS Compliant

Application

- EV Charging
- DC-AC Inverters
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives





Ordering Information

Part Number	Marking	Package	Packaging
JX4S0080065M	JX4S0080065M	TO247-4	Tube



Absolute Maximum Ratings(Tc=25℃)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage	650	V
I _D	Drain Current(continuous)at Tc=25℃	40	А
I _D	Drain Current(continuous)at Tc=100℃	20	А
I _{DM}	Drain Current (pulsed)	60	А
V _{GS}	Gate-Source Voltage	-10/+20	V
P _D	Power Dissipation T _C = 25°C	152	W
T _{J,} Tstg	Junction and Storage Temperature Range	-55 to +150	°C

Electrical Characteristics($T_J = 25^{\circ}C$ unless otherwise specified)

Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
BV _{DS}	Drain-source Breakdown	In=250uA.V _{GS} =0V	650			V
DVDS	Voltage	ID-250uA, VGS-0V	650			V
1	Zero Gate Voltage Drain	V _{DS} =650V, V _{GS} =0V,			100	uA
I _{DSS}	Current	TJ=25°C			100	uA
I _{GSS}	Gate-body Leakage Current	V_{DS} =0V ; V_{GS} =-10 to 18V			250	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =5mA	1.5		3.5	V
В	Static Drain-source On	V _{GS} =18V, I _D =20A		60	79	mΩ
R _{DS(on)}	Resistance	VGS-10V, ID-20A		00	79	11122
R _G	Gate Resistance	V _{GS} =0V,f=1MHz		3		Ω

Typical Performance-Dynamic

C _{iss}	Input Capacitance		1648	pF
Coss	Output Capacitance	V _{DS} =470V,f=1MH _Z ,V _{GS} =0V	86	pF
C _{rss}	Reverse Transfer Capacitance		12	pF
Qg	Total Gate Charge	V _{DS} =470V,	82	nC
Q _{gs}	Gate-source Charge	I _D =30A,V _{GS} =-5~20V	19	nC
Q_{gd}	Gate-Drain Charge		22	nC
t _{d(on)}	Turn-on Delay Time		19	ns
t _r	Rise Time	V _{DD} =470V,ID=30A, V _{GS} =-5V~20V.	23	ns
t _{d(off)}	Turn-off Delay Time	$R_{G}=0\Omega$.	35	ns
t _f	Fall Time	_ ,	21	ns





Typical Performance-Reverse Diode

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Fanyard Valtage	V _{GS} =0V,I _F =20A,T _J =25°C	3		6	V
V _{FSD}	Forward Voltage	V _{GS} =0V,I _F =20A,T _J =150°C	3		6	V
t _{rr}	Reverse Recovery Time	V - 5 V I -20 A		31		ns
Qrr	Reverse Recovery Charge	V_{GS} =-5 V, I _F =20 A, V_{R} =470 V.		242		nC
	Peak Reverse Recovery	V _R =470 V, d <i>i</i> /d <i>t</i> = -1000 A/μs		18		Α
Irrm	Current	αιιαι - 1000 Α/μ3		10		A

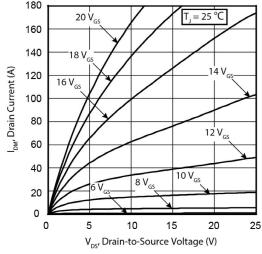
Thermal Characteristics

Symbol	Parameter	Value.	Unit
Rejc	Thermal Resistance, Junction-to-Case	0.82	°C/W
Reja	Thermal Resistance, Junction-to-Case	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of Tj(max)=150 $^{\circ}$ C



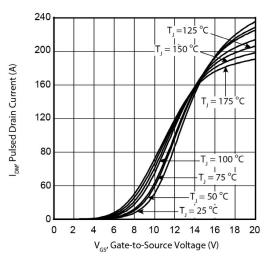
Electrical Characteristics (25°C unless noted)



T, = 150 °C 20 V_{GS} 160 140 18 V_G _{low}, Drain Current (A) 120 16 V_{GS} 12 V_G 100 80 10 V_G 60 40 8 V_{GS} 20 0 10 15 25 $V_{DS'}$ Drain-to-Source Voltage (V)

Figure 1: Output characteristics (T_J = 25 °C)





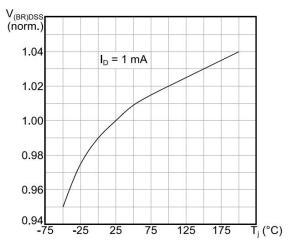
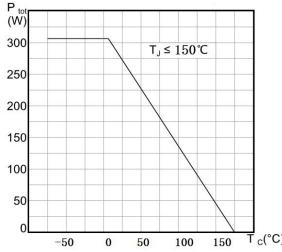


Figure 3: Transfer characteristics

Figure 4 Normalized BVDSS vs. Temperature



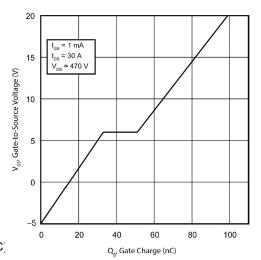
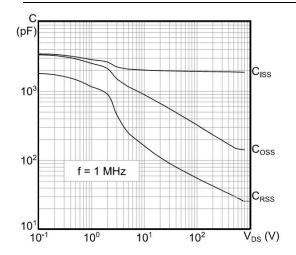


Figure 5: Power dissipation

Figure 6: Gate charge vs gate-source voltage





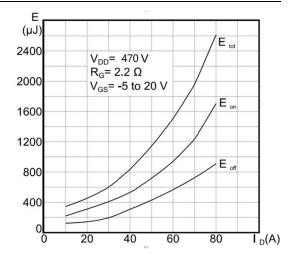


Figure 7: Capacitance variations

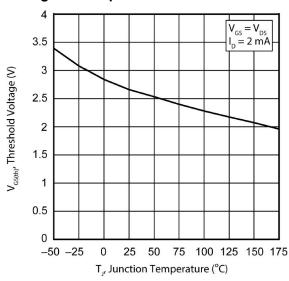


Figure 8: Switching energy vs. drain current

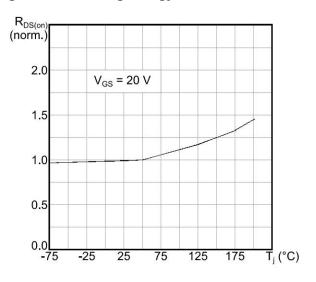


Figure 9: Normalized Vth vs. TJ

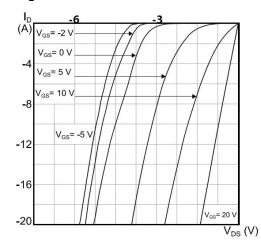


Figure 11: Body diode characteristics $(T_J = 25 \, ^{\circ}C)$

Figure 10: Normalized Rdson vs. TJ

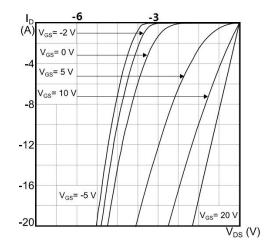


Figure 12: Body diode characteristics ($T_J = 150$ °C)



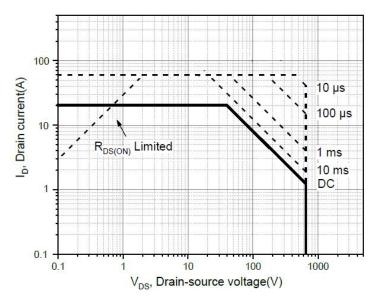
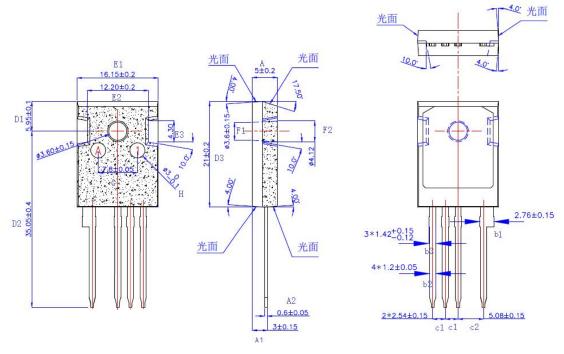


Figure 13: Safe operating area



Package Drawing:



Dimensions (UNIT: mm)

SYM	MILLIMETERS		SYM	MILLIMETERS	
	MIN	MAX		MIN	MAX
A	4.98	5.02	D2	34.65	35.45
A1	2.85	3.15	D3	20.80	21.20
A2	0.55	0.65	E1	15.95	16.35
b1	2.61	2.91	E2	12.00	12.40
b2	1.15	1.25	F1	3.45	3.75
b3	1.30	1.57	F2	4.12	4.12
c1	2.39	2.69	G	7.75	7.85
c2	4.93	5.23	Н	2.90	3.10
D1	5.85	6.05			